

Technical Data
Data Sheet N1125, Rev. A

Green Products

Marking Diagram:



Where XXXXX is YYWWL

SDUR = Device Type
D = Package type
10 = Forward Current (10A)
40 = Reverse Voltage (400V)
SSG = SSG
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Ordering Information:

Device	Package	Shipping
SDURD1040	DPAK (Pb-Free)	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	V_{RWM}	-	400	V
Max. Average Forward	$I_{F(AV)}$	50% duty cycle @TC =100°C rectangular wave form	10	A
Max. Peak One Cycle Non-Repetitive Surge Current	I_{FSM}	8.3 ms, half Sine pulse	125	A

Electrical Characteristics:

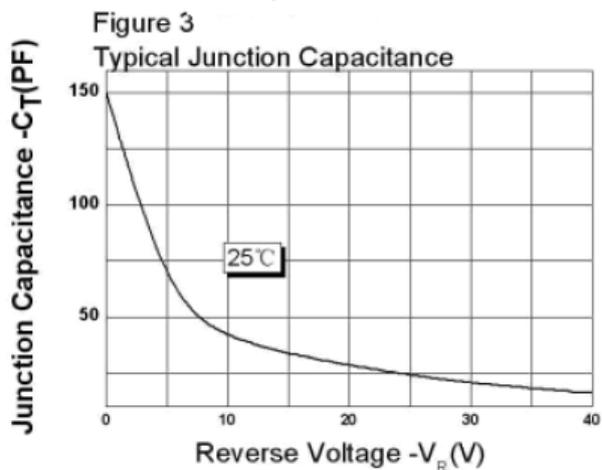
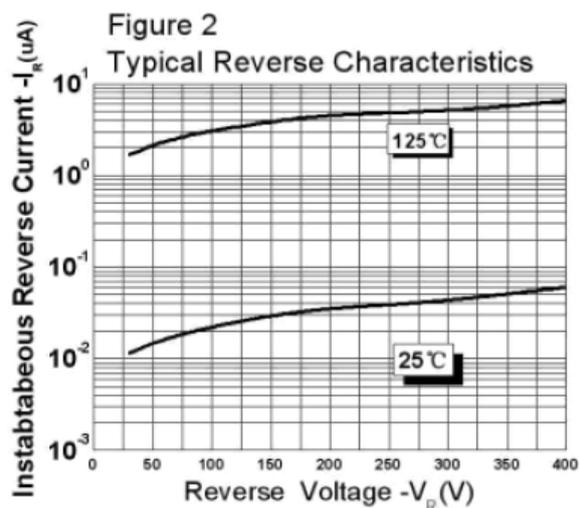
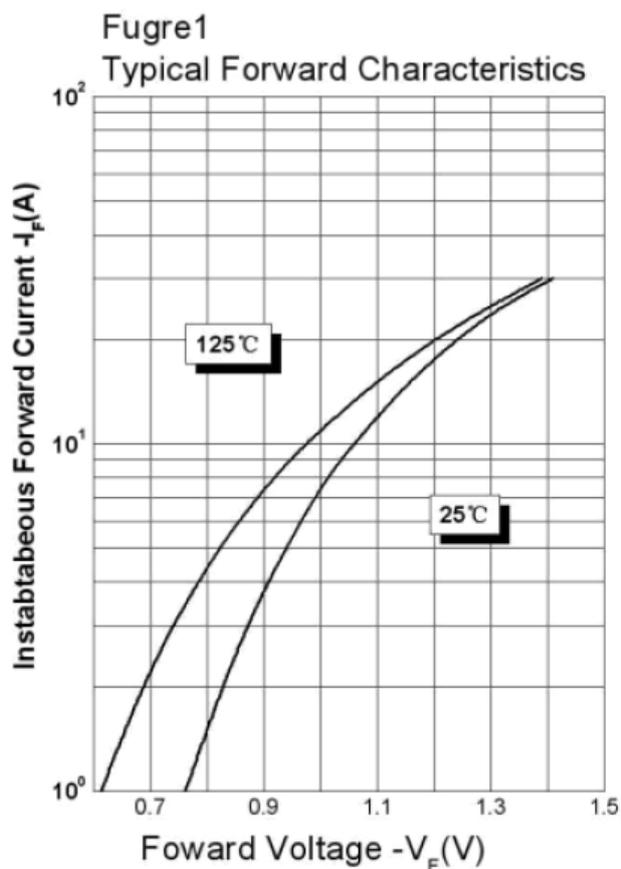
Characteristics	Symbol	Condition	Max.	Units
Max. Forward Voltage Drop	V_{F1}	@ 10A, Pulse, $T_J = 25^\circ\text{C}$	1.5	V
	V_{F2}	@ 10 A, Pulse, $T_J = 100^\circ\text{C}$	1.4	V
Max. Reverse Current	I_{R1}	@ $V_R = \text{rated VR}$ $T_J = 25^\circ\text{C}$	10	μA
	I_{R2}	@ $V_R = \text{rated VR}$ $T_J = 125^\circ\text{C}$	500	μA
Max. Reverse Recovery Time	t_{rr}	$I_F=500\text{mA}$, $I_R=1\text{A}$, and $I_{rm}=250\text{mA}$	45	ns

* Pulse Width < 300 μs , Duty Cycle <2%

Measured lead to lead 5 mm from package body

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Max. Junction Temperature	T_J	-	-55 to +150	$^\circ\text{C}$
Max. Storage Temperature	T_{stg}	-	-55 to +150	$^\circ\text{C}$
Maximum Thermal Resistance Junction to Case	$R_{\theta JC}$	DC operation	5.0	$^\circ\text{C/W}$
Approximate Weight	wt	-	0.39	g
Case Style	DPAK			



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